Product End-of-Life Disassembly Instructions

Product Category: Calculators
Marketing Name / Model [List multiple models if applicable.]
HP MSR2003 AC Router （JG411A）

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

PSG instructions for this template are available at EL-MF877-01

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew all screws 1, and then remove the mounting angle 2.
2. Unscrew the screws on card 3, and then remove card 3.
3. Unscrew the screws on cover 4, and then remove cover 4.
4. Unscrew the screws on part 5, and then remove part 5.
5. Unscrew all screws 6, and then remove partl 7.
6. Unscrew the Power Cable Holder 8
7. Remove plastic panel 9 from chassis 16.
8. Remove plastic panel 10 from chassis 16.
9. Unscrew the screws on power bracket 11, and then remove power bracket 11.
10. Remove screws 12 from the chassis.
11. Unscrew the screws on PCB 13, and then remove PCB 13.
12. Remove partl 14 from the chassis.
13. Remove plastic panel 15 from the chassis.
14. Unscrew the screws on fan 5-2, and then remove fan 5-2.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

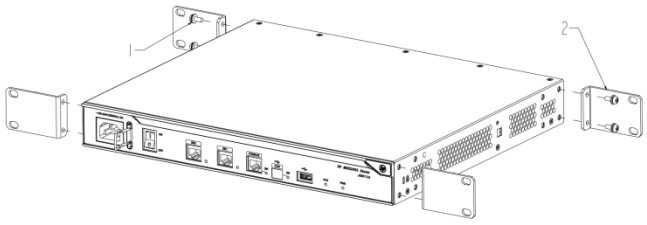

Figure 1 Treatments to the product

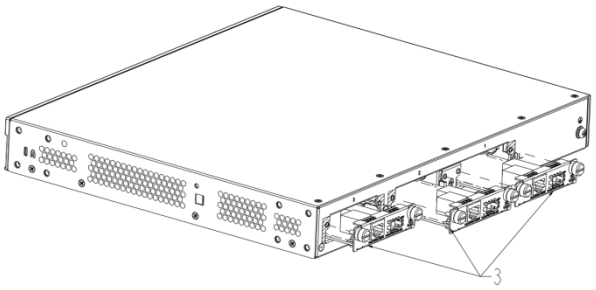

Figure 2 Treatments to the product

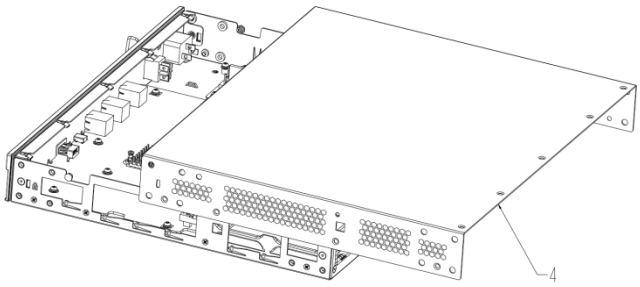

Figure 3 Treatments to the product

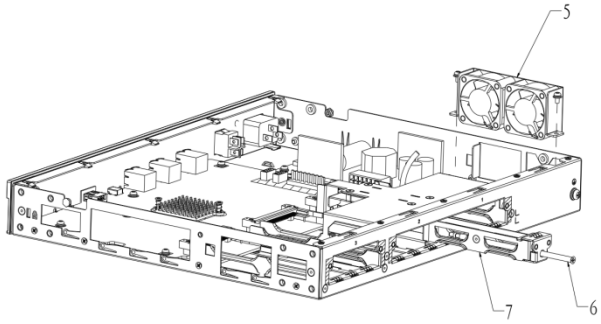

Figure 4 Treatments to the product

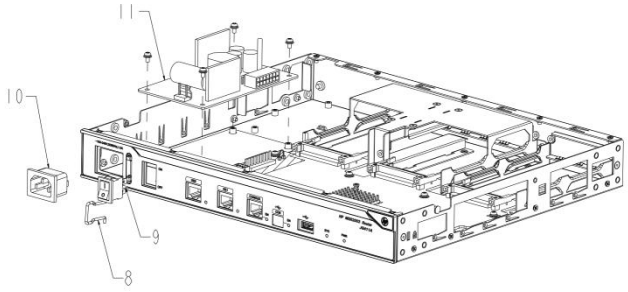

Figure 5 Treatments to the product

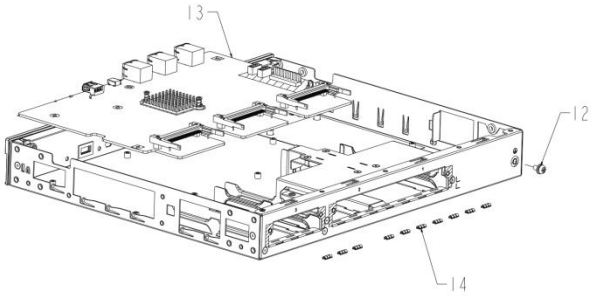

Figure 6 Treatments to the product

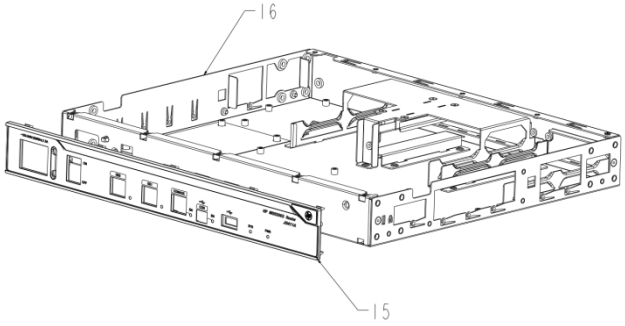

Figure 7 Treatments to the product

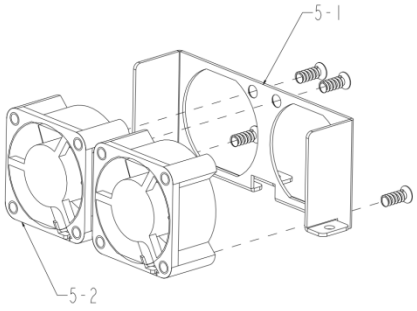

Figure 8 Treatments to the product

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
	2	Fe	56.2	1.6%		Fe recycling
	4	Fe	1096.8	32.4%		Fe recycling
5						
	5-2	PBT , Cu	33*2	1.8%	Containing brominated flame retardants	Pla recycling Cu recycling
	5-1	Fe	29.6	0.8%		Fe recycling
	7	Fe	54.1	1.4%		Fe recycling
	11	PBT , Cu	328	9.7%	Containing brominated flame retardants	Pla recycling Cu recycling
	13	Complex PWB	350	9.9%	The surface of PCB is greater than 10 square centimeters;	

	15	PBT	50	1.4%		Pla recycling
	16	Fe	1477.4	40.9%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2012.12.11	V0	Liu Jia	Initial version